

## Analog Devices Inc, Moving from Ink Mark to Laser Mark

### Qualification Results and Summary of Laser Top Mark Cerpak for RH and SMD devices

TEST	SPECIFICATION TO MIL-STD-883	SAMPLE SIZE TOTAL OF 3 LOTS	RESULTS
B/1a	Physical Dimensions Method 2016	2 units	PASS
B/1b	Internal Water Vapor Method 1018	3 units	PASS
B/2b	Internal Visual and Mechanical Method 2013/2014	2 units	PASS
B/2c	Bond Pull Method 2011	22 bonds	PASS
B/2d	Die Shear Method 2019	3 units	PASS
B/3	Solderability Method 2003	42 leads	PASS
B/4a	Lead Integrity Method 2004, Cond. B2	45 leads	PASS
B/4b	Fine Leak/Gross Leak Method 1014, Cond. A and C	5 units	PASS
B/4c	Lid Torque Method 2024	5 units	PASS
B/6	Pre-test 3 temp.	17 units	PASS
	Temp. Cycling Method 1010, Cond. C	17 units	PASS
	Constant Acceleration Method 2001, Cond. E	17 units	PASS
	Fine Leak/Gross Leak Method 1014, Cond. A and C	17 units	PASS
	Post-test 3 temp.	17 units	PASS
D/3	Pre-test 3 temp.	17 units	PASS
	Thermal Shock Method 1011, Cond. B	17 units	PASS
	Temperature Cycling Method 1010, Cond. C	17 units	PASS
	Moisture Resistance Method 1004	17 units	PASS
	Fine Leak/Gross Leak Method 1014, Cond. A and C	17 units	PASS

D/3	Visual Examination Method 1004/1010	17 units	PASS
	Post-test 3 temp.	17 units	PASS
D/5	Salt Atmosphere Method 1009, Cond. A	15 units	PASS
	Fine Leak/Gross Leak Method 1014, Cond. A and C	15 units	PASS
	Visual Examination Method 1009	15 units	PASS